

ABSTRACT OF THE DISCLOSURE

A semiconductor device which has a main circuit board equipped with primary modules such as a CPU and an I/O sub-system chip and a first sub-circuit-board equipped with a main memory. The main circuit board is connected to the first sub-circuit-board through an FPC. Further, a first TCP equipped with the CPU and a second TCP equipped with the I/O sub-system chip are mounted on both of the top and bottom surface of the main circuit board in such a manner that the second TCP is placed just behind the first TCP. The semiconductor device is used as a card type computer by bending the FPC and facing the main circuit board to the sub-circuit-board and enclosing the main circuit board and the sub-circuit-board in a card-shaped thin housing. Thereby, reduction in size and thickness of the semiconductor device can be achieved. Further, a high density packaging can be realized. Moreover, an operation of the semiconductor device can be performed at a high speed. Furthermore, the performance of the semiconductor device can be easily and most appropriately changed in a short time at a low cost without changing the primary modules only by replacing the sub-circuit-board with another circuit board.